

C0G with KONNEKT Technology

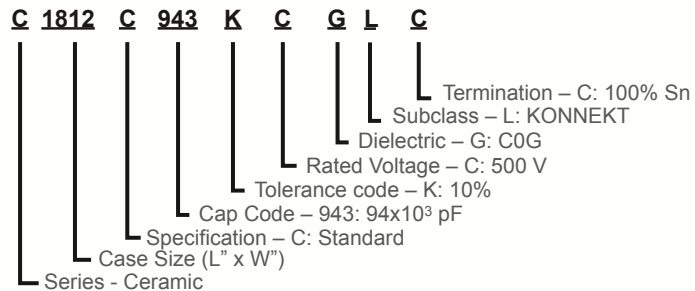
Overview

C0G with KONNEKT™ technology surface-mount capacitors are designed for high-efficiency and high-density power applications. KONNEKT high density packaging technology uses an innovative Transient Liquid Phase Sintering (TLPS) material to create a surface-mount multi-chip solution for high density.

Benefits

- Commercial and Automotive Grade
- Wide voltage and capacitance range
- Stable capacitance with temperature, frequency, and voltage
- Surface-mount capable with standard reflow
- No piezoelectric noise

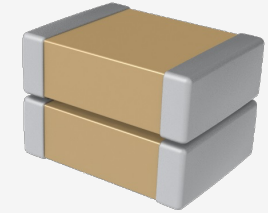
Part Number System



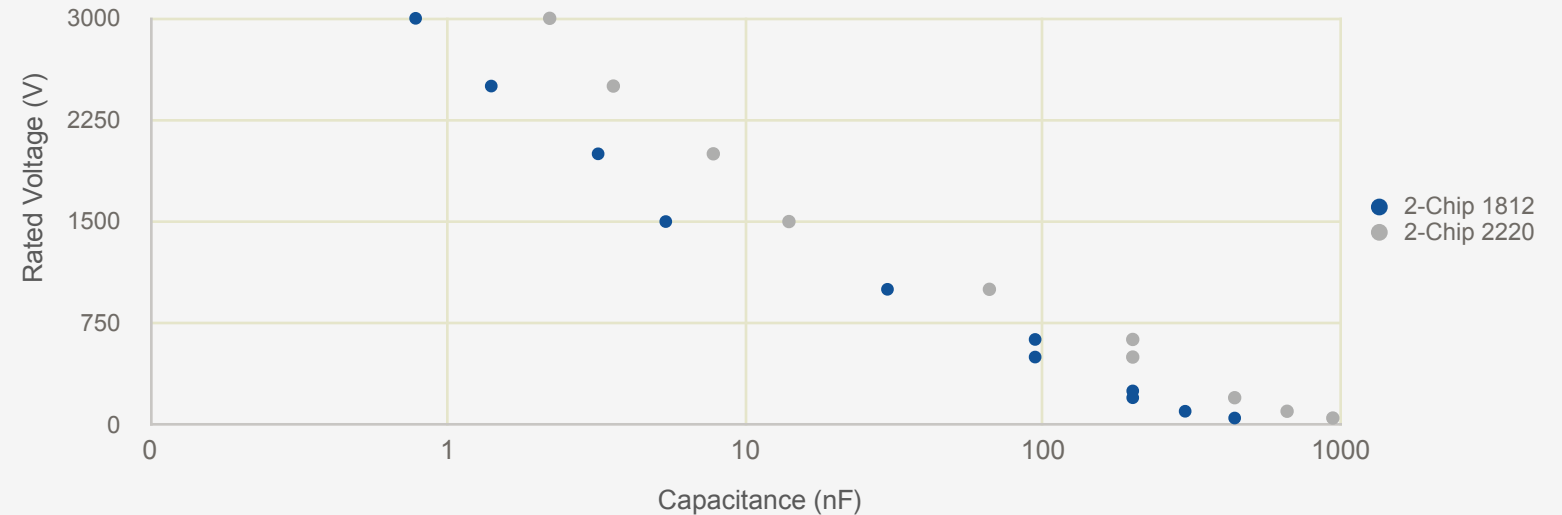
Electrical Characteristics

Operating Temperature	-55°C to +125°C
Rated Capacitance	0.78 nF – 940 nF (±10% tol.)
Rated Voltage	50 V – 3,000 V
EIA Case Size	1812 and 2220

Standard Orientation



Selection Guide



Applications

Wide bandgap (WBG), silicon carbide (SiC) and gallium nitride (GaN) systems
 EV/HEV (drive systems, charging)
 LLC resonant converters
 Switch tank converters

Data centers
 Wireless charging systems
 Power converters
 Timing

<https://www.kemet.com/en/us/new-products.html>